

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jun. 19, 2012

Expected First Date Code of Changed Product :2512

Last Date for Shipment of Unchanged Product : Jun. 19, 2012

Description of Change (From) :
FDMC8588 Power 33 package with exposed top metal slug.

Description of Change (To) :
Converting the FDMC8588 to our standard Power 33 package by removing the exposed top metal slug.

Reason for Change:

This change is to the manufacturing process by removing the exposed top metal slug for Fairchild product FDMC8588 assembled in the Power 33 package. There are no changes to the currently approved assembly facilities or any other materials used to manufacture these products. Package outline drawings, footprints, and recommended land patterns remain unchanged for the affected products. Electrical parameters and Silicon die are not affected. Junction-to-slug thermal characteristics are being removed from the datasheet. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing products.

Affected Product(s):

FDMC8588		
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A qualification plan for PCN

Qualification Plan	Device	Package	Process	No. of Lots
QP11060882-B	FDMC7582	PQFN 3x3 Clip	PT7 MOSFET	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260°C, 3 cycles	JESD22-A113		0/474
Highly Accelerated Stress Test	130°C, 85%RH, Vr = 20V	JESD22-A110	96 hrs	0/237
Power Cycle	T on/off = 2min, Delta Tj = 100°C	JESD22-A105	10000 cycles	0/237
Temperature Cycle	-65°C to 150°C, 15min dwell	JESD22-A104	500 cycles	0/237
High Temperature Reverse Bias	150°C, Vr = 20V	JESD22-A108	1000 hrs	0/237
High Temperature Gate Bias	150°C, Vgs = 20V	JESD22-A108-B	1000 hrs	0/237

Qualification Plan	Device	Package	Process	No. of Lots
EQPP 11-016A	FDMC7660	PQFN 3x3 Clip	PT7 MOSFET	2

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260°C, 3 cycles	JESD22-A113		0/154
Power Cycle	T on/off = 2min, Delta Tj = 100°C	JESD22-A105	10000 cycles	0/154
Temperature Cycle	-65°C to 150°C, 15min dwell	JESD22-A104	500 cycles	0/154

Qualification Plan	Device	Package	Process	No. of Lots
QP11270939-D	FDMC8588	PQFN 3X3 Clip	PT8+ MOSFET	2

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260°C, 3 cycles	JESD22-A113		0/154
Highly Accelerated Stress Test	130°C, 85%RH, Vr = 20V	JESD22-A110	96 hrs	0/77
Temperature Cycle	-65°C to 150°C, 15min dwell	JESD22-A104	500 cycles	0/154
High Temperature Reverse Bias	150°C, Vr = 20V	JESD22-A108	1000 hrs	0/154
High Temperature Gate Bias	150°C, Vgs = 12V	JESD22-A108-B	1000 hrs	0/154